



## Material Content Data Sheet



Sales Product Name	TLS835B2EL VSE			Issued		16. January 2020		
MA#	MA002813174							
Package	PG-SSOP-14-5			Weight*		82.71 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.221	1.48	1.48	14763	14763
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		417	
	non noble metal	iron	7439-89-6	0.689	0.83		8331	
	non noble metal	copper	7440-50-8	27.978	33.83	34.71	338263	347115
wire	non noble metal	copper	7440-50-8	0.054	0.06	0.06	647	647
encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1222	
	plastics	epoxy resin	-	4.649	5.62		56208	
	inorganic material	silicondioxide	60676-86-0	45.782	55.35	61.09	553525	610955
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11802	11802
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9281	9281
glue	plastics	epoxy resin	-	0.112	0.14		1359	
	noble metal	silver	7440-22-4	0.337	0.41	0.55	4078	5437
*deviation	< 10%	Sum in total:			100.00			1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com